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ON Semiconductor

October 2016

# FAM65V05DF1 Auto SPM<sup>®</sup> Series Automotive 3-Phase IGBT Smart Power Module

## Features

- 27 pin Auto SPM<sup>®</sup> module
- 650 V-50 A 3-phase IGBT module with low loss IGBTs and soft recovery diodes optimized for motor control applications
- Integrated gate drivers with Internal V<sub>S</sub> connection, Under Voltage lockout, Over-current shutdown, Temperature Sensing Unit and Fault reporting
- Electrically isolated AIN substrate with low R<sub>thjc</sub>
- Module serialization for full traceability
- Pb-Free and RoHS compliant
- UL Certified No. E209204 (UL 1557)
- Automotive qualified

## General Description

FAM65V05DF1 is an advanced Auto SPM<sup>®</sup> module providing a fully-featured high-performance auxiliary inverter output stage for hybrid and electric vehicles. These modules integrate optimized gate drive of the built-in IGBTs to minimize EMI and losses, while also providing various protection features, in a compact 12cm<sup>2</sup> footprint.

## Applications Note

[AN-8422](#) – 650 V Auto SPM<sup>®</sup> Series; Automotive 3-Phase IGBT Smart Power Module User's Guide

## Applications and Benefits

Automotive high voltage auxiliary motors such as air conditioning compressor and oil pump

- Compact design
- Simplified PCB layout and low EMI
- Simplified Assembly
- High reliability



Figure 1. Package view

## Ordering Information

Part Number	Marking	Package	Packing Method	Qty. per tube	Qty. per box
FAM65V05DF1	FAM65V05DF1	APM27-CAA	Tube	10	60

## Pin Configuration

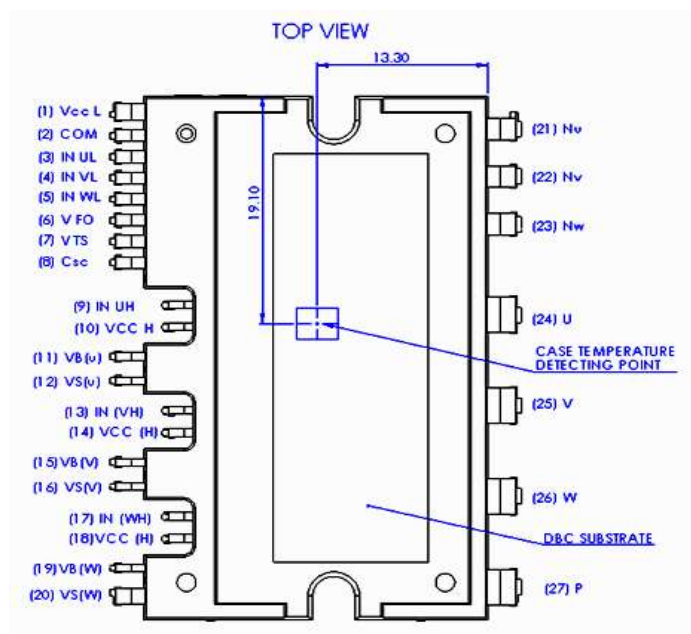


Figure 2. Pin configuration

## Pin Description

Pin Number	Pin	Pin Function Description
1	VCC(L)	Low-side Common Bias Voltage for IC and IGBTs Driving
2	COM	Common Supply Ground
3	IN (UL)	Signal Input for Low-side U Phase
4	IN (VL)	Signal Input for Low-side V Phase
5	IN (WL)	Signal Input for Low-side W Phase
6	VFO	Fault Output
7	VTS	Output for LVIC temperature sense
8	CSC	Capacitor (Low-pass Filter) for Short-Current Detection Input
9	IN (UH)	Signal Input for High-side U Phase
10	VCC(H)	High-side Common Bias Voltage for IC and IGBTs Driving
11	VB(U)	High-side Bias Voltage for U Phase IGBT Driving
12	VS(U)	High-side Bias Voltage Ground for U Phase IGBT Driving
13	IN(VH)	Signal Input for High-side V Phase
14	VCC(H)	High-side Common Bias Voltage for IC and IGBTs Driving
15	VB(V)	High-side Bias Voltage for V Phase IGBT Driving
16	VS(V)	High-side Bias Voltage Ground for V Phase IGBT Driving
17	IN(WH)	Signal Input for High-side W Phase
18	VCC(H)	High-side Common Bias Voltage for IC and IGBTs Driving
19	VB(W)	High-side Bias Voltage for W Phase IGBT Driving
20	VS(W)	High-side Bias Voltage Ground for W Phase IGBT Driving
21	NU	Negative DC-Link Input for U Phase
22	NV	Negative DC-Link Input for V Phase
23	NW	Negative DC-Link Input for W Phase
24	U	Output for U Phase
25	V	Output for V Phase
26	W	Output for W Phase
27	P	Positive DC-Link Input

## Internal Equivalent Circuit and Input/Output Pins

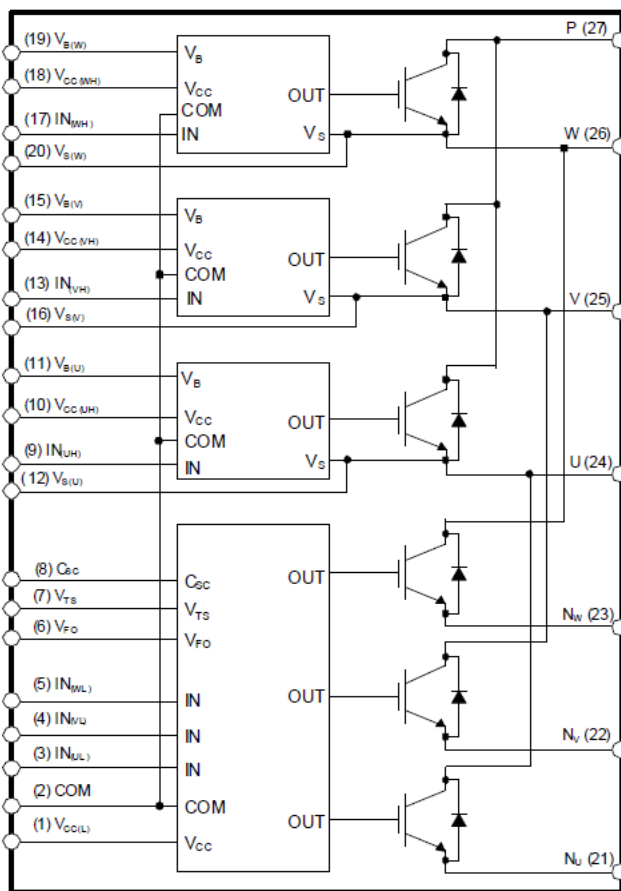


Figure 3. Schematic

## Gate drivers block diagram

High side gate driver (x3 single channel):

- Control circuit under-voltage (UV) protection
- 3.3/5 V CMOS/LSTTL compatible, Schmitt trigger input

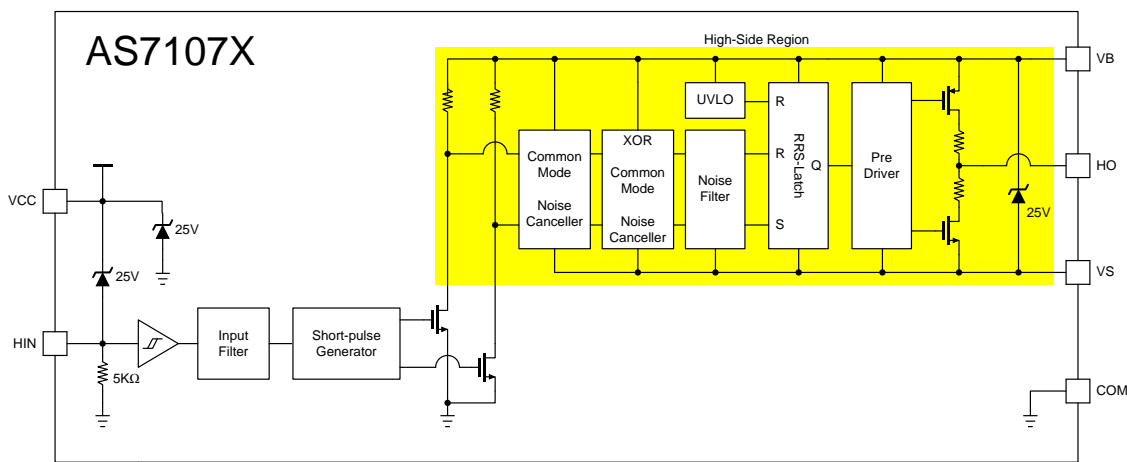


Figure 4. High Side gate drivers (block diagram)

Low side gate driver (x1 monolithic three-channel):

- Control circuit under-voltage (UV) protection
- Short circuit protection (SC)
- Temperature sensing unit
- Fault Output
- 3.3/5 V CMOS/LSTTL compatible, Schmitt trigger input

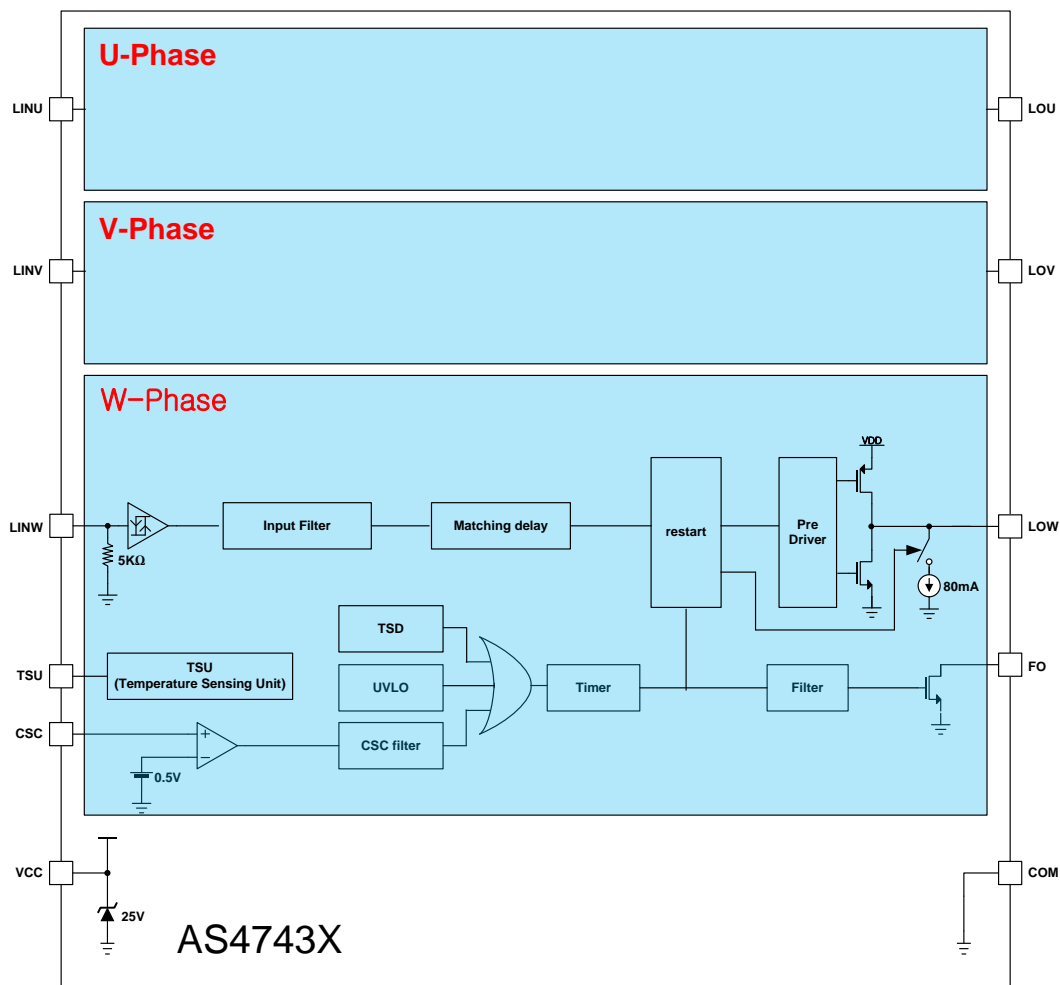


Figure 5. Low Side gate drivers (block diagram)

**Absolute Maximum Ratings** ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)

Stresses exceeding the Absolute Maximum Ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability.

**Inverter Part**

Symbol	Parameter	Condition	Rating	Unit
$V_{PN}$	Supply voltage	Applied between P- $N_U$ , $N_V$ , $N_W$	500	V
$V_{PN(\text{Surge})}$	Supply Voltage (surge)	Applied between P- $N_U$ , $N_V$ , $N_W$ $di/dt \leq 3\text{A/ns}$	575	V
$V_{CES}$	Collector-emitter Voltage at the IGBT/diode	$T_J=25^\circ\text{C}$	650	V
$\pm I_C$	IGBT continuous collector current	$T_C = 100^\circ\text{C}$ , $T_{J\text{max}}=175^\circ\text{C}$ (Note1)	50	A
$\pm I_{CP}$	IGBT peak collector pulse current	$T_C = 25^\circ\text{C}$ , $T_{J\text{max}}=175^\circ\text{C}$ , $V_{CC}=V_{BS}=15\text{V}$ , less than 1ms (Note 6)	150	A
$P_C$	Collector Dissipation	$T_C = 25^\circ\text{C}$ per IGBT	333	W
$T_J$	Junction Temperature	IGBT/Diode	-40 ~ +175	$^\circ\text{C}$
		Driver IC	-40 ~ +150	$^\circ\text{C}$

**Control Part**

Symbol	Parameter	Condition	Rating	Unit
$V_{CC}$	Control Supply Voltage	Applied between $V_{CC(H)}$ , $V_{CC(L)}$ - COM	20	V
$V_{BS}$	High-side Control Bias Voltage	Applied between $V_{B(U)}$ - $V_{S(U)}$ , $V_{B(V)}$ - $V_{S(V)}$ , $V_{B(W)}$ - $V_{S(W)}$	20	V
$V_{IN}$	Input Signal Voltage	Applied between $IN_{(UH)}$ , $IN_{(VH)}$ , $IN_{(WH)}$ , $IN_{(UL)}$ , $IN_{(VL)}$ , $IN_{(WL)}$ - COM	-0.3 ~ $V_{CC}+0.3$	V
$V_{FO}$	Fault Output Supply Voltage	Applied between $V_{FO}$ - COM	-0.3 ~ $V_{CC}+0.3$	V
$I_{FO}$	Fault Output Current	Sink Current at $V_{FO}$ Pin	5	mA
$V_{SC}$	Current Sensing Input Voltage	Applied between $C_{SC}$ - COM	-0.3 ~ $V_{CC}+0.3$	V
$V_{TS}$	Temperature sense unit		-0.3 ~ $2/3 \times V_{CC}$	V

**Total System**

Symbol	Parameter	Condition	Rating	Unit
$T_{STG}$	Storage Temperature		-40 ~ 125	$^\circ\text{C}$
$V_{ISO}$	Isolation Voltage	60Hz, Sinusoidal, AC 1 minute, Connection Pins to heat sink plate	2500	$V_{rms}$
$T_{LEAD}$	Max lead temperature at the base of the package during pcb assembly	No remelt of internal solder joints	200	$^\circ\text{C}$

**Package Characteristics**

Symbol	Parameter	Conditions	Typ.	Max.	Units
$R_{th(j-c)Q}$	Junction to Case Thermal Resistance <sup>(2)</sup>	Inverter IGBT part (per IGBT)	-	0.45	$^\circ\text{C/W}$
$R_{th(j-c)F}$		Inverter FWD part (per DIODE)	-	0.85	$^\circ\text{C/W}$
$L_G$	Package Stray Inductance	P to $N_U$ , $N_V$ , $N_W$ <sup>(3)</sup>	24	-	nH

**Notes:**

- Current limited by package terminal, defined by design
- Case temperature measured below the package at the chip center, compliant with MIL STD 883-1012.1 (single chip heating), DBC discoloration allowed, please refer to application note [AN-9190](#) (Impact of DBC Oxidation on SPM® Module Performance)
- Stray inductance per phase measured per IEC 60747-15

## Electrical Specifications

### Inverter part (T<sub>J</sub> as specified)

Symbol	Parameters	Conditions	Min	Typ	Max	Unit	
V <sub>CE(SAT)</sub>	Collector-Emitter Saturation Voltage	V <sub>CC</sub> = V <sub>BS</sub> = 15 V, V <sub>IN</sub> = 5 V I <sub>C</sub> = 50 A, T <sub>J</sub> = 25°C	-	1.65	-	V	
		V <sub>CC</sub> = V <sub>BS</sub> = 15 V, V <sub>IN</sub> = 5 V I <sub>C</sub> = 50 A, T <sub>J</sub> = 125°C	-	1.9	2.4	V	
V <sub>F</sub>	FWD Forward Voltage	V <sub>IN</sub> = 0 V, I <sub>F</sub> = 30 A, T <sub>J</sub> = 25°C	-	2.1	-	V	
		V <sub>IN</sub> = 0 V, I <sub>F</sub> = 30 A, T <sub>J</sub> = 125°C	-	1.9	2.5	V	
HS	High Side Switching Times	V <sub>PN</sub> = 300 V, V <sub>CC</sub> = V <sub>BS</sub> = 15 V I <sub>C</sub> = 50 A V <sub>IN</sub> = 0 V ↔ 5V, L <sub>s</sub> =55 nH, Inductive Load T <sub>J</sub> = 25°C <sup>(4, 5)</sup>	-	0.73	-	μs	
			t <sub>C(ON)</sub>	-	0.12		-
			t <sub>OFF</sub>	-	0.80		-
			t <sub>C(OFF)</sub>	-	0.14		-
			t <sub>rr</sub>	-	0.10		-
	High Side Switching Times	V <sub>PN</sub> = 300 V, V <sub>CC</sub> = V <sub>BS</sub> = 15 V I <sub>C</sub> = 50 A V <sub>IN</sub> = 0 V ↔ 5V, L <sub>s</sub> =55 nH, Inductive Load T <sub>J</sub> = 125°C <sup>(4, 5)</sup>	-	0.70	-	μs	
			t <sub>C(ON)</sub>	-	0.15		-
			t <sub>OFF</sub>	-	0.87		-
			t <sub>C(OFF)</sub>	-	0.19		-
			t <sub>rr</sub>	-	0.20		-
LS	Low Side Switching Times	V <sub>PN</sub> = 300 V, V <sub>CC</sub> = V <sub>BS</sub> = 15 V I <sub>C</sub> = 50 A V <sub>IN</sub> = 0 V ↔ 5 V, L <sub>s</sub> =55 nH, Inductive Load T <sub>J</sub> = 25°C <sup>(4, 5)</sup>	-	0.68	-	μs	
			t <sub>C(ON)</sub>	-	0.20		-
			t <sub>OFF</sub>	-	0.86		-
			t <sub>C(OFF)</sub>	-	0.19		-
			t <sub>rr</sub>	-	0.14		-
	Low Side Switching Times	V <sub>PN</sub> = 300 V, V <sub>CC</sub> = V <sub>BS</sub> = 15 V I <sub>C</sub> = 50 A V <sub>IN</sub> = 0 V ↔ 5 V, L <sub>s</sub> =55 nH, Inductive Load T <sub>J</sub> = 125°C <sup>(4, 5)</sup>	-	0.64	-	μs	
			t <sub>C(ON)</sub>	-	0.24		-
			t <sub>OFF</sub>	-	0.88		-
			t <sub>C(OFF)</sub>	-	0.23		-
			t <sub>rr</sub>	-	0.20		-
SCWT	Short Circuit withstand time <sup>(6)</sup>	V <sub>CC</sub> = V <sub>BS</sub> = 15 V, V <sub>PN</sub> = 450 V, T <sub>J</sub> = 25°C, Non-repetitive	-	5	-	μs	
I <sub>CES</sub>	Collector-Emitter Leakage Current for IGBT and diode in parallel	T <sub>J</sub> = 25°C, V <sub>CE</sub> = 650 V	-	3	-	μA	
		T <sub>J</sub> = 125°C, V <sub>CE</sub> = 650 V	-	150	1500	μA	

#### Notes:

- t<sub>ON</sub> and t<sub>OFF</sub> include the propagation delay time of the internal drive IC. t<sub>C(ON)</sub> and t<sub>C(OFF)</sub> are the switching times of IGBT itself under the given gate driving condition internally. Refer to Figure 6 for detailed information
- Stray inductance L<sub>s</sub> is sum of stray inductance of module & setup
- Verified by design and bench-testing only

**Control Part** ( $T_J = -40^{\circ}\text{C}$  to  $150^{\circ}\text{C}$ , unless otherwise specified, typical values specified at  $T_J=125^{\circ}\text{C}$ )

Symbol	Parameters	Conditions	Min	Typ	Max	Unit
$I_{QCCL}$	Quiescent $V_{CC}$ Supply Current	$V_{CC} = 15\text{ V}$ , $I_{N(U,L, VL, WL)} = 0\text{ V}$			5	mA
$I_{QCCH}$		$V_{CC} = 15\text{ V}$ , $I_{N(UH, VH, WH)} = 0\text{ V}$			150	$\mu\text{A}$
$I_{PCCH}$	Operating $V_{CC}$ Supply Current	$V_{CC(UH, VH, WH)} = 15\text{ V}$ $f_{PWM} = 20\text{ kHz}$ Duty=50%, applied to one PWM signal input for high-side			0.30	mA
$I_{QCCL}$		$V_{CC(UH, VH, WH)} = 15\text{ V}$ $f_{PWM} = 20\text{ kHz}$ Duty=50%, applied to one PWM signal input for low-side			8.5	mA
$I_{QBS}$	Quiescent $V_{BS}$ Supply Current	$V_{BS} = 15\text{ V}$ , $I_{N(UH, VH, WH)} = 0\text{ V}$			150	$\mu\text{A}$
$I_{PBS}$	Operating $V_{BS}$ Supply Current	$V_{CC}=V_{BC}=15\text{ V}$ $I_{N(UH, VH, WH)} = 0\text{ V}$			4.5	mA
$V_{FOH}$	Fault Output Voltage	$V_{SC} = 0\text{ V}$ , $V_{FO}$ Circuit: 4.7 k $\Omega$ to 5 V Pull-up	4.5	-	-	V
$V_{FOL}$		$V_{SC} = 1\text{ V}$ , $V_{FO}$ Circuit: 4.7 k $\Omega$ to 5 V Pull-up	-	-	0.5	V
$V_{SC(ref)}$	Short-Circuit Trip Level	$V_{CC} = 15\text{ V}^{(7)}$	0.45	0.52	0.59	V
$UV_{CCD}$	Supply Circuit Under-Voltage Protection	Detection Level, $T_J = 125^{\circ}\text{C}$	10.6	-	13.2	V
$UV_{CCR}$		Reset Level, $T_J = 125^{\circ}\text{C}$	11.0	-	13.8	V
$UV_{BSD}$		Detection Level, $T_J = 125^{\circ}\text{C}$	10.5	-	13	V
$UV_{BSR}$		Reset Level, $T_J = 125^{\circ}\text{C}$	10.8	-	13.3	V
$t_{FOD}$	Fault-out Pulse Width		-	60	-	$\mu\text{s}$
$V_{TS}$	LVIC Temperature Sensing Voltage Output	$V_{CC(L)} = 15\text{ V}$ , $T_{LVIC} = 125^{\circ}\text{C}^{(8)}$	-	2.4	-	V
$V_{IN(ON)}$	ON Threshold Voltage	Applied between $I_{N(UH)}$ , $I_{N(VH)}$ , $I_{N(WH)}$ , $I_{N(UL)}$ , $I_{N(VL)}$ , $I_{N(WL)} - \text{COM}$	-	2.6	3.1	V
$V_{IN(OFF)}$	OFF Threshold Voltage		0.9	1.2	-	V

**Notes:**

7. Short-circuit current protection is functional only for low side
8.  $T_{LVIC}$  is the junction temperature of the LVIC itself



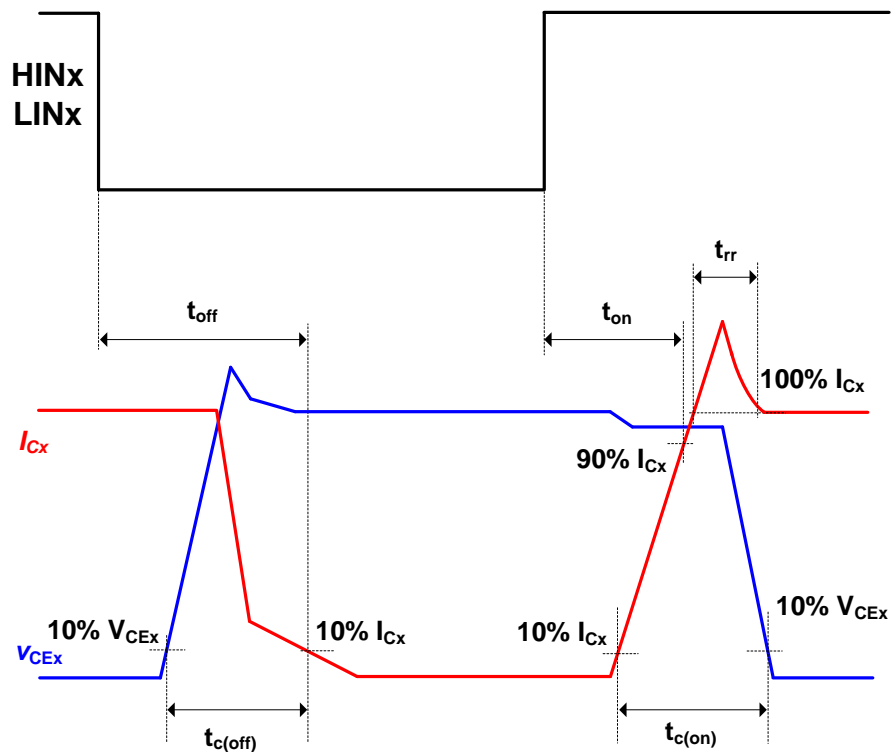


Figure 6a. Switching Time Definition

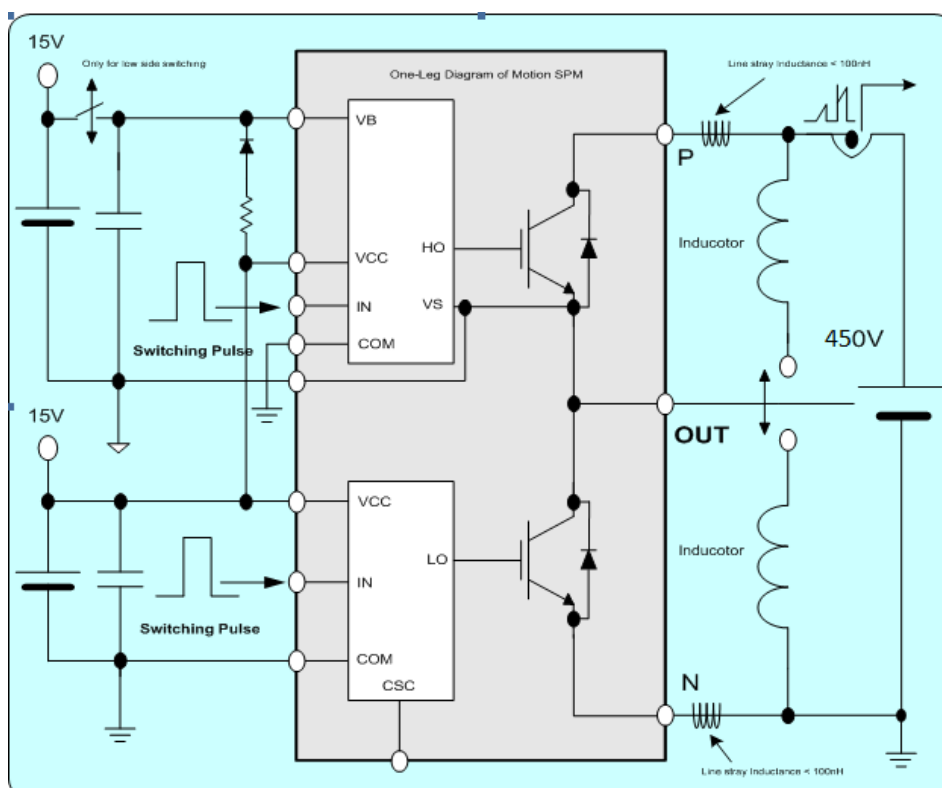


Figure 7b. Switching Evaluation Circuit

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended Operating Conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameters	Conditions	Min	Typ	Max	Unit
$V_{PN}$	Supply Voltage	Applied between P - $N_U$ , $N_V$ , $N_W$	-	450	500	V
$V_{CC}$	Control Supply Voltage	Applied between $V_{CC(H)}$ , $V_{CC(L)}$ - COM	13.5	15	16.5	V
$V_{BS}$	High-side Bias Voltage	Applied between $V_{B(U)}$ - $V_{S(U)}$ , $V_{B(V)}$ - $V_{S(V)}$ , $V_{B(W)}$ - $V_{S(W)}$	13.3	15	18.5	V
$dV_{CC}/dt$ , $dV_{BS}/dt$	Control supply variation		-1	-	1	V/ $\mu$ s
$t_{dead}$	Blanking Time for Preventing Arm-short	For Each Input Signal	1.0	-	-	$\mu$ s
$f_{PWM}$	PWM Input Signal	$T_C = 125^\circ\text{C}$	-	-	20	kHz
$V_{SEN}$	Voltage for Current Sensing	Applied between $N_U$ , $N_V$ , $N_W$ - COM (Including surge voltage)	-4	-	4	V
$T_J$	Junction temperature		-40	-	150	$^\circ\text{C}$

## Mechanical Characteristics and Ratings

Parameter	Conditions	Conditions	Limits			Units
			Min.	Typ.	Max.	
Mounting Torque	Mounting Screw: - M3	Recommended 0.62N•m	0.51	0.62	0.80	N•m
Device Flatness					+150	$\mu$ m
Weight				15		g

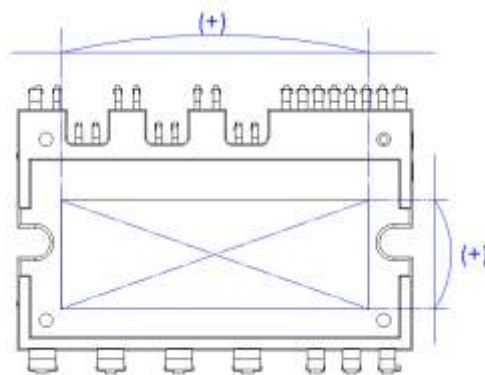
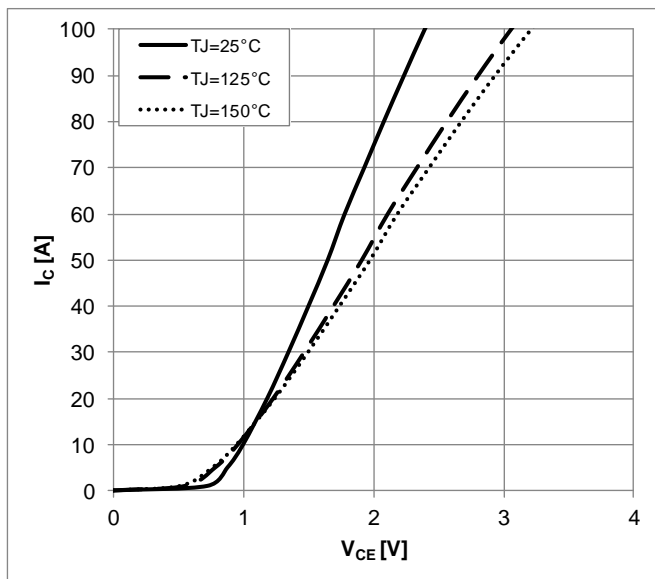
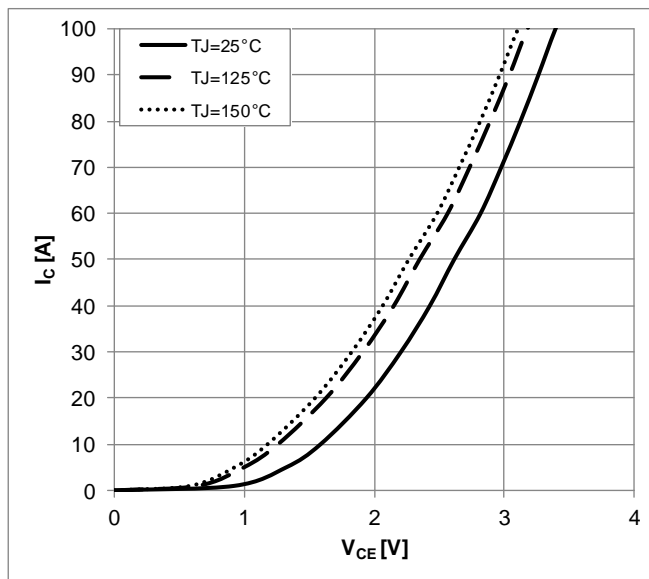


Figure 8. Flatness Measurement Position

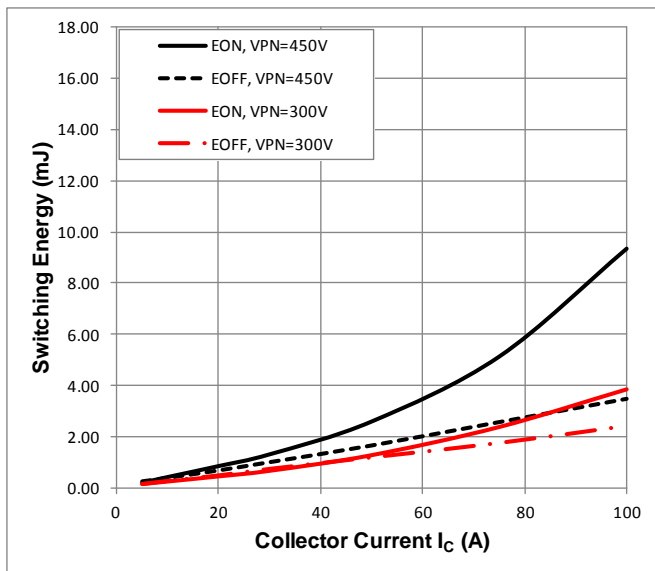
## Typical Inverter Characteristics



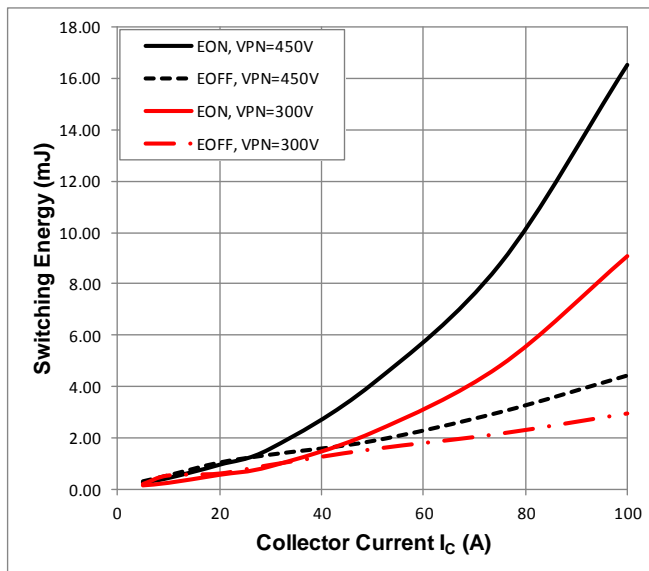
**Figure 9. Output characteristics IGBT inverter (typical)**  
 $V_{CC} = V_{BS} = 15\text{ V}$ ,  $V_{IN} = 5\text{ V}$



**Figure 10. Forward characteristics DIODE inverter (typical)**  
 $V_{IN} = 0\text{ V}$

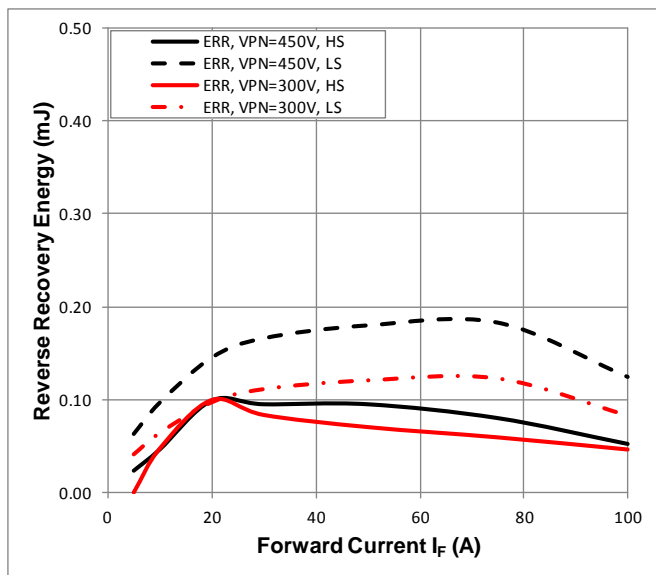


**Figure 11. Switching losses IGBT inverter High-Side (typical) versus collector current**  
 $V_{CC} = V_{BS} = 15\text{ V}$   
 $V_{IN} = 0\text{ V} \leftrightarrow 5\text{ V}$ ,  $L_s = 55\text{ nH}$ , Inductive Load,  $T_J = 125^\circ\text{C}$

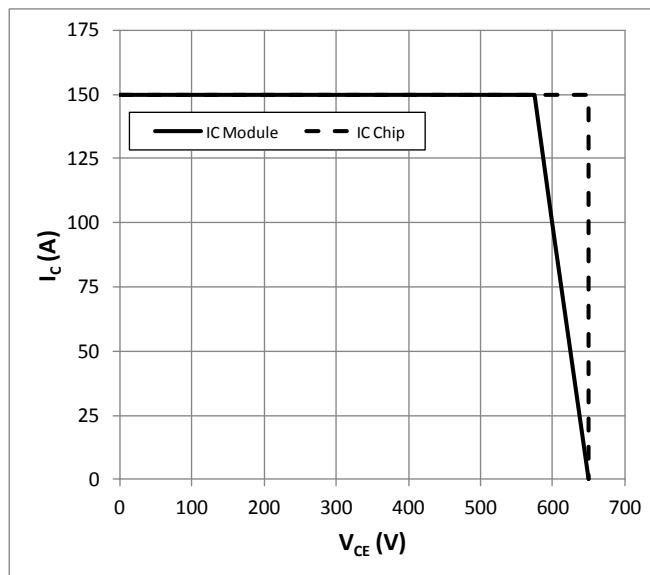


**Figure 12. Switching losses IGBT inverter Low-Side (typical) versus collector current**  
 $V_{CC} = V_{BS} = 15\text{ V}$   
 $V_{IN} = 0\text{ V} \leftrightarrow 5\text{ V}$ ,  $L_s = 55\text{ nH}$ , Inductive Load,  $T_J = 125^\circ\text{C}$

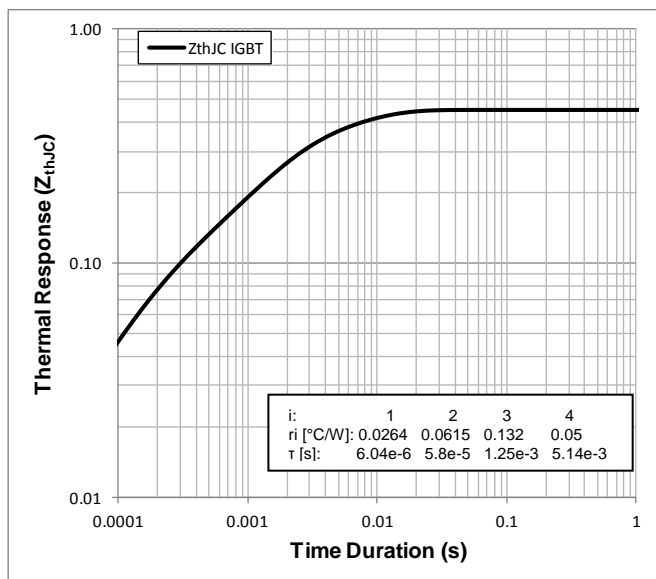
## Typical Inverter Characteristics



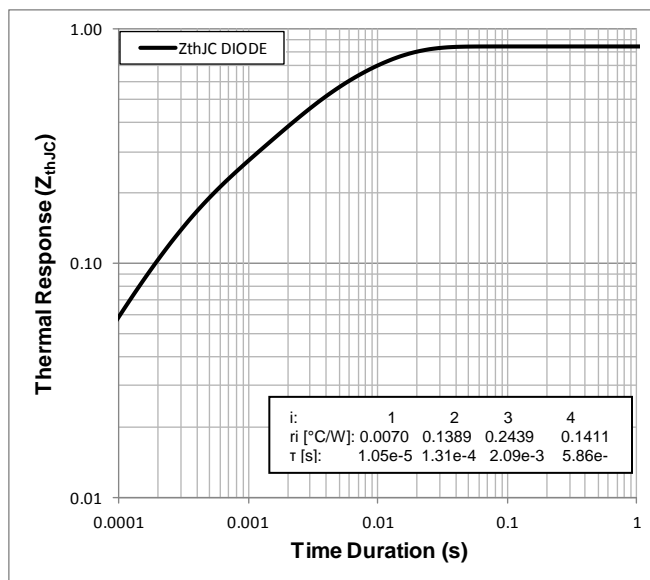
**Figure 13. Reverse recovery energy DIODE inverter (typical) versus forward current**  
 $V_{CC} = V_{BS} = 15\text{ V}$   
 $V_{IN} = 0\text{ V} \leftrightarrow 5\text{ V}$ ,  $L_s=55\text{ nH}$ , Inductive Load,  $T_J=125^\circ\text{C}$



**Figure 14. Reverse Bias Safe Operating Area IGBT (RBSOA) inverter**  
 $V_{CC} = V_{BS} = 15\text{ V}$ ,  $T_J=150^\circ\text{C}$



**Figure 15. Transient thermal impedance IGBT inverter**



**Figure 16. Transient thermal impedance DIODE inverter**

### Typical Controller Characteristics

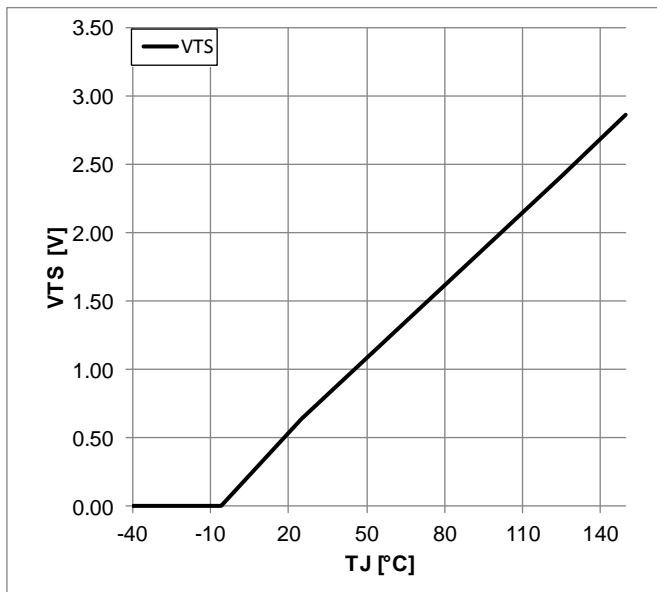


Figure 17. Temperature profile of V<sub>TS</sub> (typical)

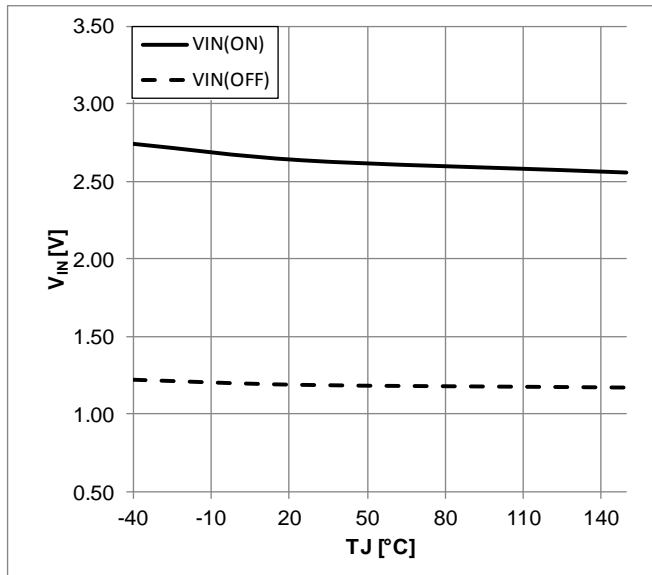


Figure 18. Threshold voltage versus temperature

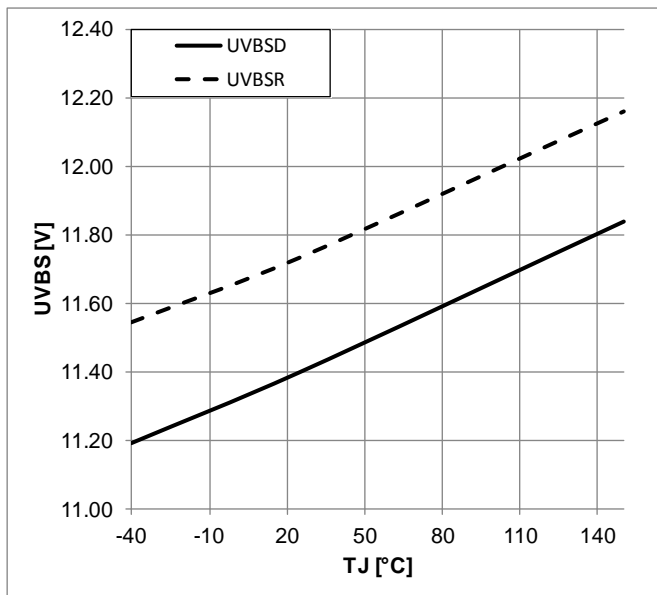


Figure 19. Supply under-voltage protection high-side (typical)

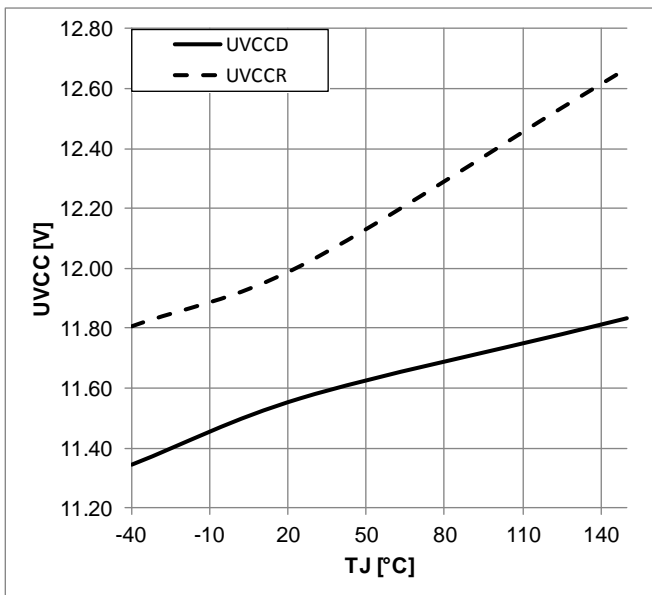
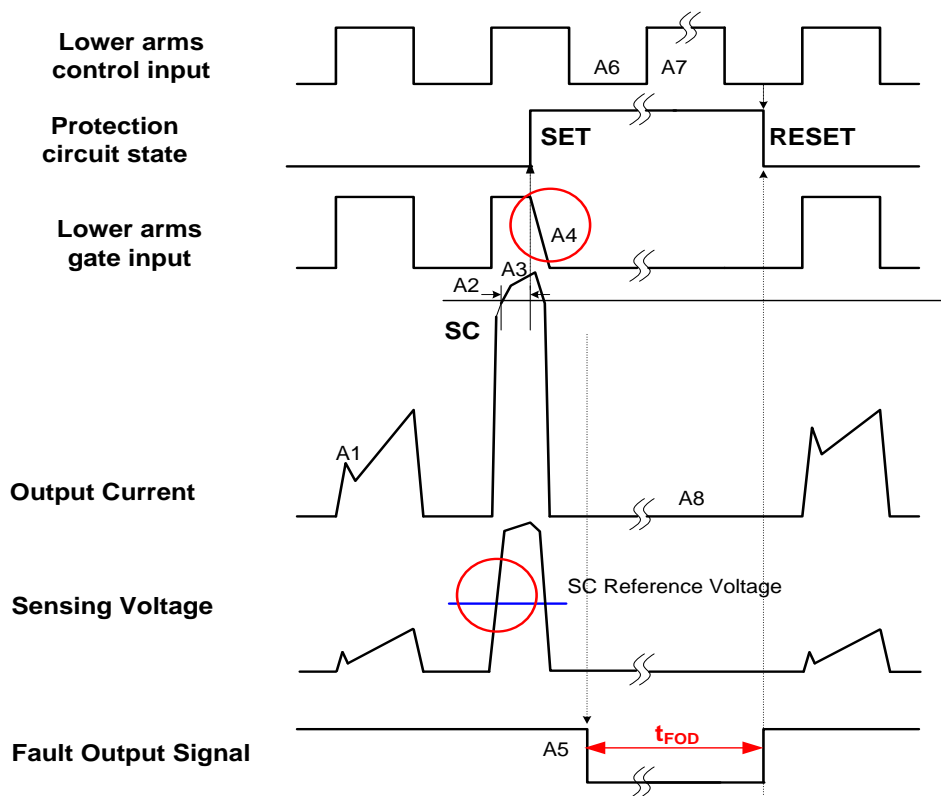


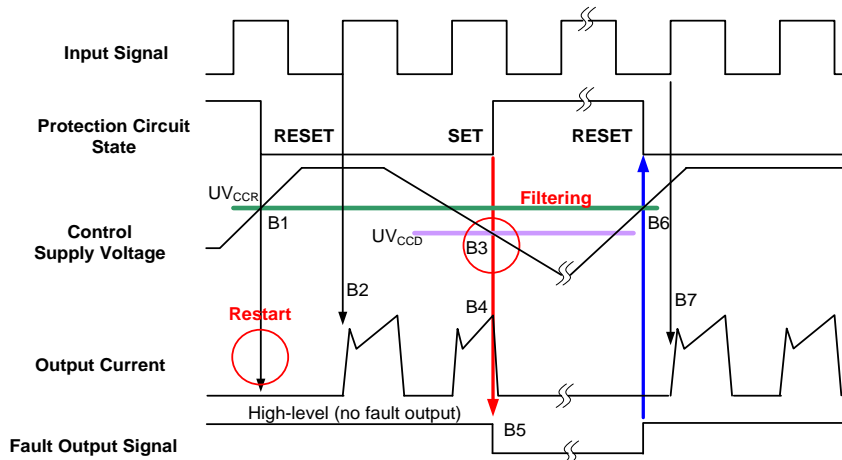
Figure 20. Supply under-voltage protection low-side (typical)

## Timing Chart Protective Functions



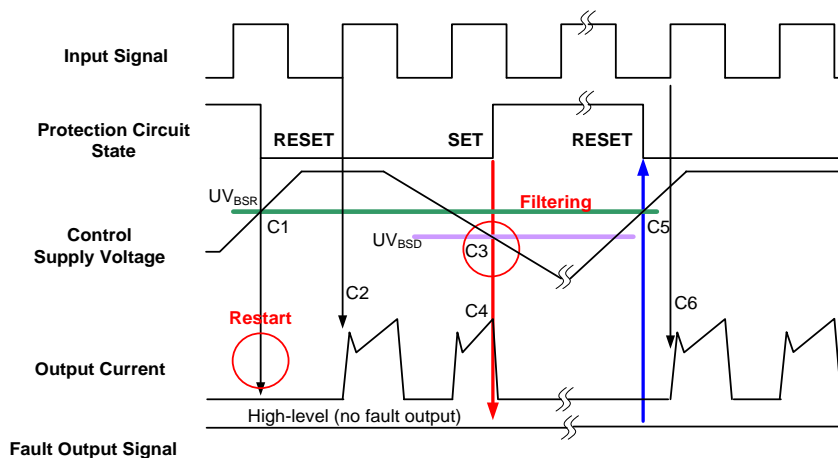
Step	Description
A1	Normal operation. IGBT on and carrying current
A2	Short-circuit current threshold reached
A3	Protection function triggered
A4	IGBT turns off with soft turn-off
A5	Fault output activated (initial delay $2 \mu\text{s}$ , $t_{\text{FOD}}$ min. $50 \mu\text{s}$ )
A6	IGBT "LO" input
A7	IGBT "HI" input is ignored
A8	Current stays at zero during fault state

**Figure 21.** Short-Circuit Current Protection



Step	Description
B1	Control supply voltage rises above reset voltage $UV_{CCR}$
B2	Normal operation. IGBT on and carrying current
B3	Control supply voltage falls below detection voltage $UV_{CCD}$
B4	Filtered supply voltage falls below $UV_{CCD}$ and IGBT turns off
B5	Fault output activated (initial delay $2 \mu s$ , $t_{FOD}$ min. $50 \mu s$ )
B6	Control supply voltage rises above reset voltage $UV_{CCR}$
B7	IGBT "HI" input is followed after fault output duration and supply voltage rise

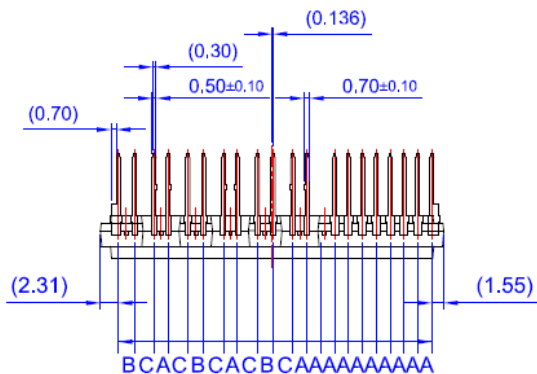
**Figure 22.** Under-Voltage Protection (Low-side)



Step	Description
C1	Control supply voltage rises above reset voltage $UV_{CCR}$
C2	Normal operation. IGBT on and carrying current
C3	Control supply voltage falls below detection voltage $UV_{CCD}$
C4	Filtered supply voltage falls below $UV_{CCD}$ and IGBT turns off
C5	Control supply voltage rises above reset voltage $UV_{CCR}$
C6	IGBT "HI" input is followed after supply voltage rise

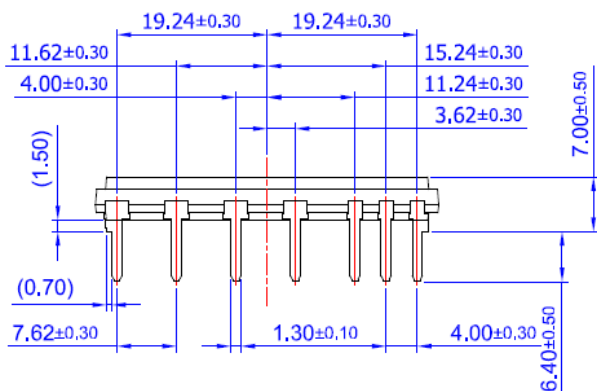
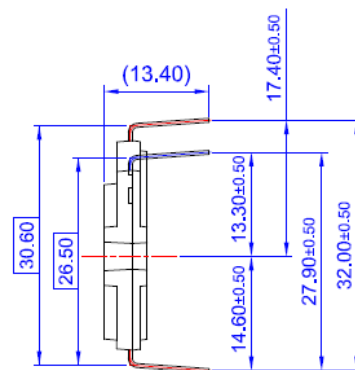
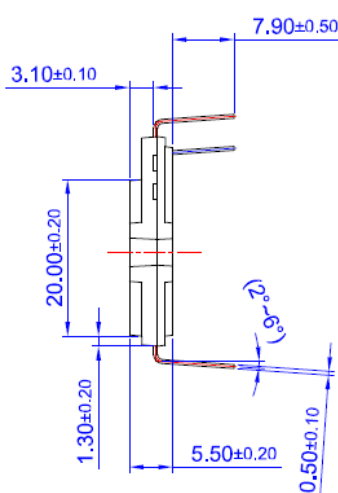
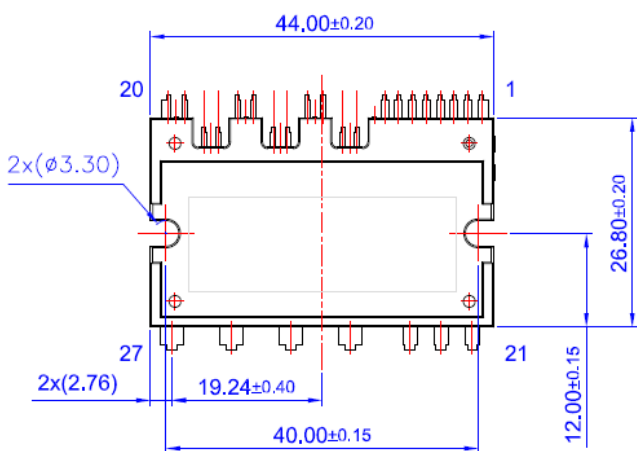
**Figure 23** Under-Voltage Protection (High-side)

**Physical Dimensions** Dimension is in millimeter unless otherwise noted.



LEAD PITCH (TOLERANCE : ±0.30)

- A : 1.778
- B : 2.050
- C : 2.531



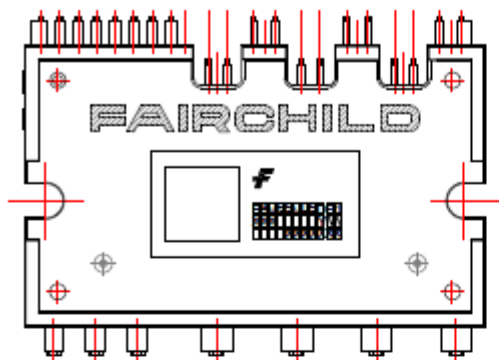
- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
  - D) ( ) IS REFERENCE
  - E) [ ] IS ASS'Y QUALITY
  - F) DRAWING FILENAME: MOD27BJREV1.0



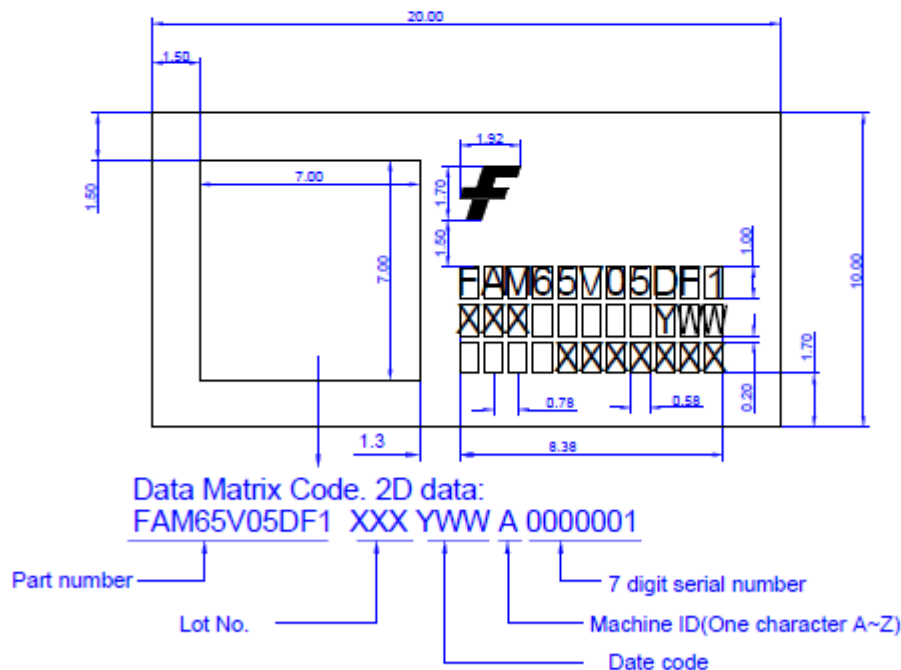


## Physical Dimensions

### \* MARKING LAY-OUT



### \* MARKING DIMENSION



X	Alphabet
2010	A
2011	B
2012	C
2013	D
2014	E
2015	F
2016	G
2017	H
2018	J
2019	K
2020	A

*Note: Marking pattern shown for final production version, which slightly differ from previous engineering versions.*

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